

10 MARCH 2023



ODDO BHF TMT Forum 2023

## Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

01

## Introduction

02

Targets 2025: Status quo

03

Ambition 2030



## SUSS MicroTec at a glance



- Hidden champion headquartered in Germany with 70+ year track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: more than € 400 million revenue and >15% EBIT margin

**SUSS is part of our digital life!**

Our corporate vision defines our strategies

SUSS MicroTec Vision

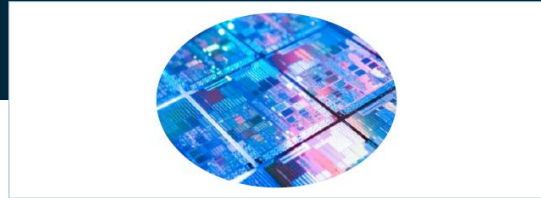
**Leader in enabling innovative  
advanced backend & photomask  
solutions.**

## Wafer fabrication



## Front-end-of-line

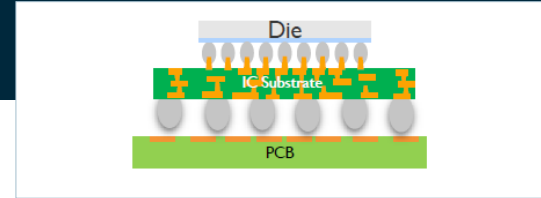
Wafer process



- Deposition/coating
- Cleaning
- **Patterning/lithography**<sup>1</sup>
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

## From middle-of-line to back-end-of-line

Advanced packaging



- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer-level packaging**
- Wafer dicing
- Panel-level packaging

## Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

<sup>1</sup> Only related to Photomask processing

Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

# Advanced Backend Solutions as core asset in our product portfolio

## Frontend

Segments Photomask Equipment



Products

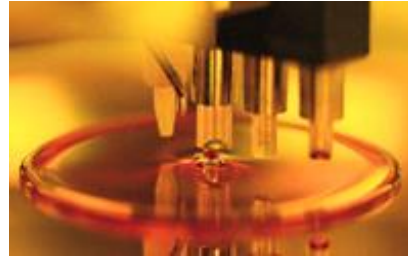
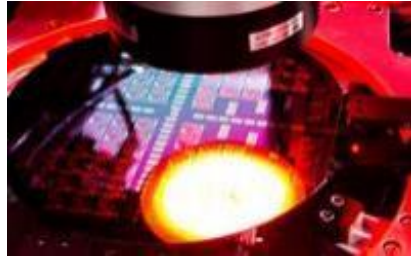
### Photomask Equipment



MaskTrack X

## Advanced backend

Advanced Backend Solutions<sup>1</sup>



### Imaging

Mask Aligner  
MA200/300



Projection  
Scanner  
DSC300

### Coating



ACS300

### Bonding

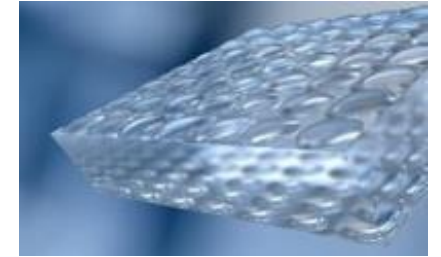
XBC300



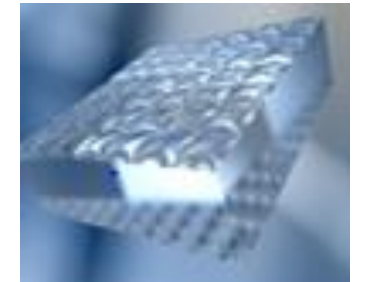
XB8

## Components

MicroOptics



### Microlens Arrays



Microlens Arrays

1) Business units Lithography and Bonder were merged into the new Advanced Backend Solutions business unit at the end of 2022. We will report in the new structure from the 2023 financial year onwards.

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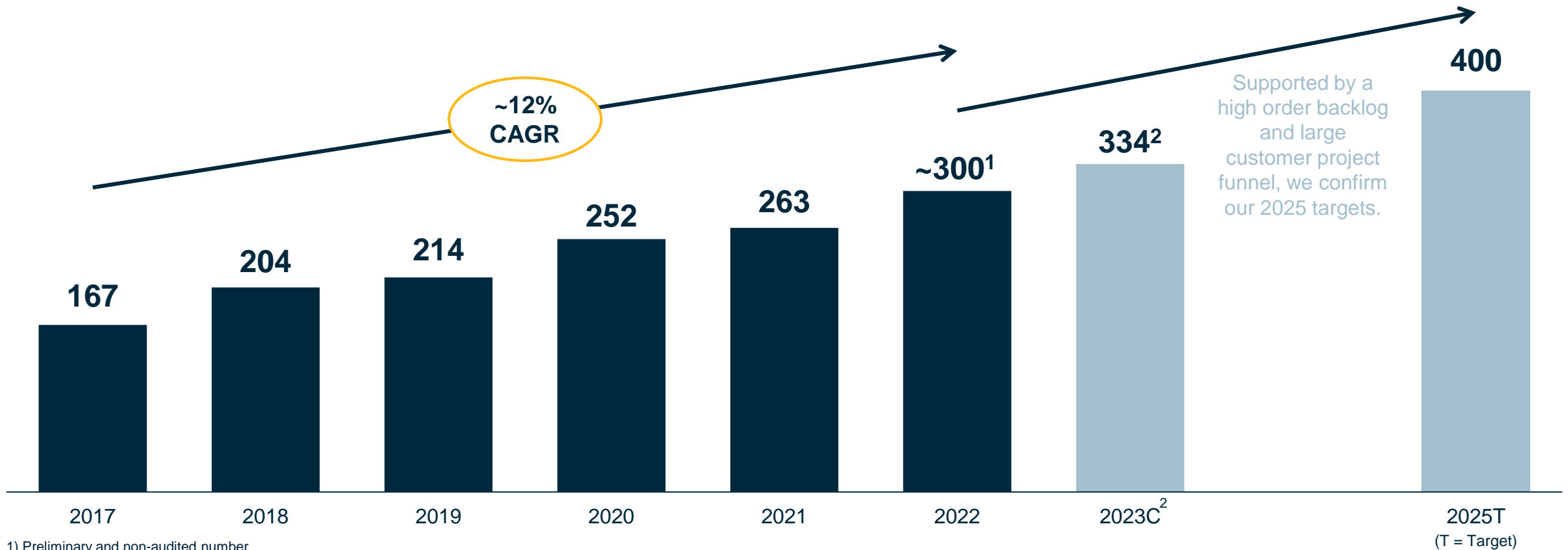


# Corporate status: We confirm our Targets for 2025

## Our target 2025

Confirmed

### Revenue of €400 million with an EBIT margin of 15%



1) Preliminary and non-audited number

2) Analysts' consensus FY 2023 sales as of 21 February 2023 = € 334.4 million

# Granted investment in global chip factories boosts semi equipment industry

Our target 2025

Revenue of €400 million with an EBIT margin of 15%

Confirmed



**Biden signs \$280 billion CHIPS and Science Act**



/ The bill includes \$52 billion in semiconductor subsidies

By MAKENA KELLY / @makemkelly  
Aug 9, 2022, 4:07 PM GMT+2 | 0 Comments | 0 News



**TECHSPOT**

**The EU Chips Act: €43 billion to build a new European chipmaking industry**

After the US, the European Union is working on its own Chips Act

By Alfonso Manuella December 6, 2022 at 7:42 AM | 11 comments



**asia financial**

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Semiconductors

**China Seen Planning \$143 Billion Push to Boost Local Chipmakers**

December 13, 2022

China plans a massive package to support its computer chip sector and will reportedly outlay over \$143 billion over five years



**Bloomberg**

Technology

**Taiwan Passes Its Chips Act, Offers Tax Credits to Chipmakers**

- A quarter of chip firms' R&D expenses can be deducted from tax
- Major governments are racing to build chip plants at home

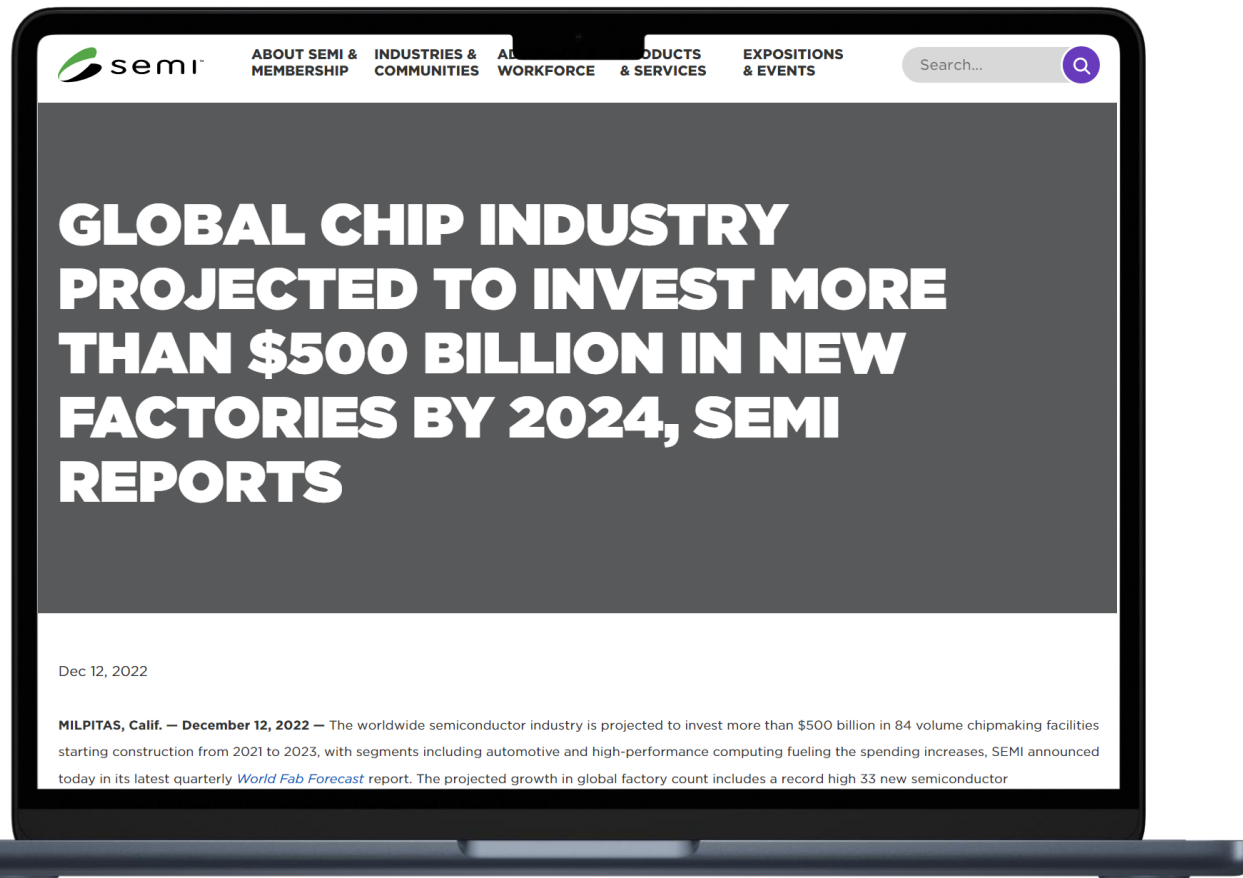
By Debby Wu  
9. Januar 2023 um 03:26 MEZ Updated on 9. Januar 2023 um 06:04 MEZ

# Mid-term investment of the semiconductor industry is well filled

Our target 2025

Revenue of €400 million with an EBIT margin of 15%

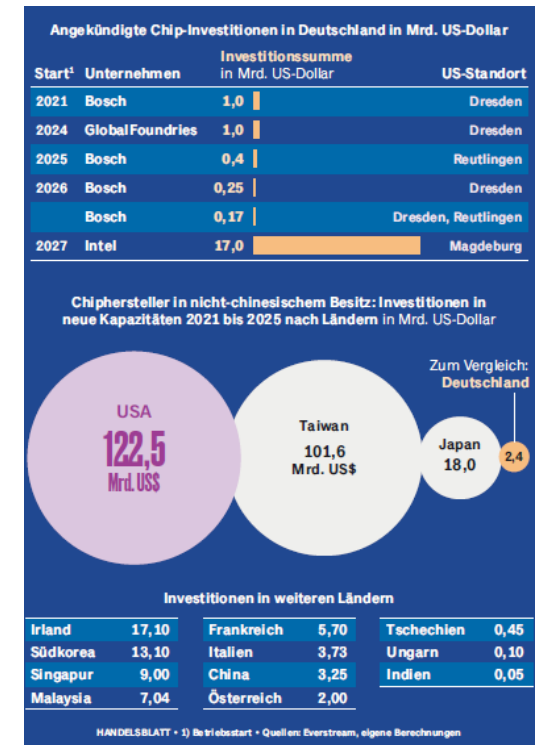
Confirmed



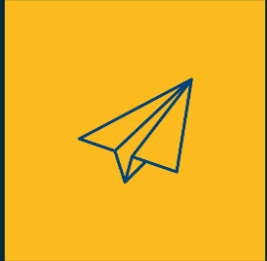
### Mega-Investments

Angekündigte Chip-Investitionen in den USA in Mrd. US-Dollar

Start <sup>1</sup>	Unternehmen	Investitionssumme in Mrd. US-Dollar	US-Standort
2021	NXP	0,1	Arizona
2022	Wolfspeed	1,0	New York
	Texas Instruments	3,5	Texas
	On Semi	0,4	New York
	Infineon	0,7	Texas
2023	Texas Instruments	3,5	Texas
	Intel	3,5	New Mexico
	GlobalFoundries	1,0	New York
2024	Intel	10,0	Arizona
	TSMC	12,0	Arizona
	Intel	10,0	Arizona
	Samsung	17,0	Texas
	Texas Instruments	3,5	Texas
	Wolfspeed	1,3	North Carolina
	Wolfspeed	5,0	North Carolina
2025	SK Hynix	15,0	TBD
	Micron	15,0	Idaho
	Texas Instruments	3,5	Texas
	Intel	10,0	Ohio
	Intel	10,0	Ohio
2026	TSMC	28,0	Arizona
2027	SK Siltron	0,6	Georgia



Q4-2022 has demonstrated that our margin target is achievable



## Target 2025

Revenue: **€400 million**  
EBIT margin: **>15%**

### Q4-2022 benchmark

Revenue: **~€105 million**  
EBIT margin: **~20%**



## Requirement

Gross profit: **39 – 40%**  
OPEX limit per quarter: **€25 million**

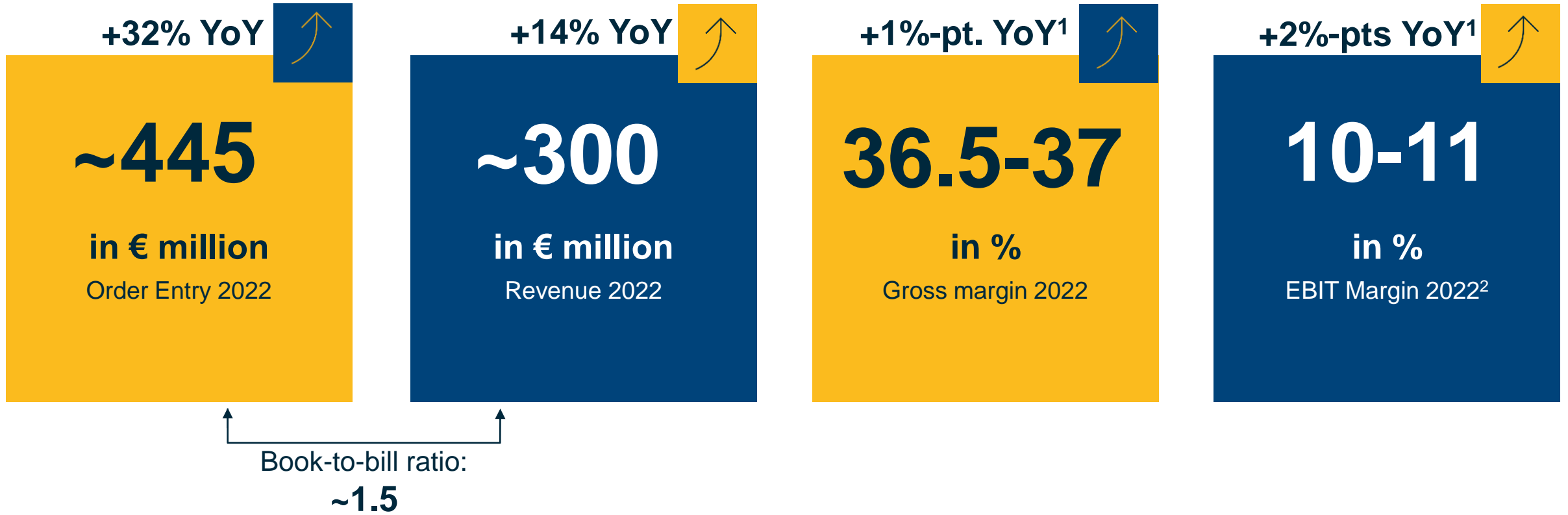
### Q4-2022 benchmark

Gross profit: **~40%**  
OPEX: **~€23 million**

# Our successful year 2022 at a glance

## Financial Results 2022

on a preliminary and non-audited basis



1) Calculation of year-on-year changes vs. 2022 based on mid-point of indicated gross margin and EBIT margin ranges; 2) including one-off effects

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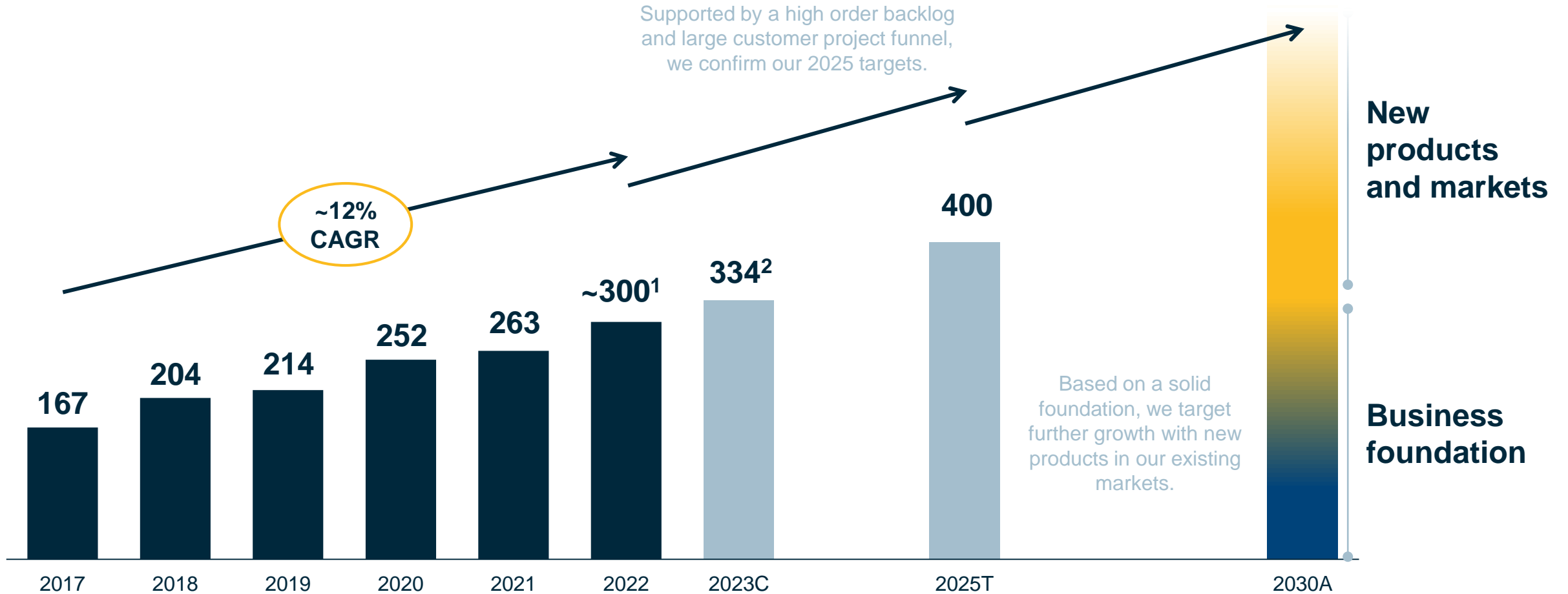
03

Ambition 2030

# Summary of our strategic directives

	<h2>Imaging Systems</h2>	<ul style="list-style-type: none"> <li>▪ Mask Aligner</li> <li>▪ Scanner</li>   <li>▪ Imprint</li> </ul>	<p>→ Maintain business volume by increasing share and higher scanner penetration (against stepper)</p> <p>→ <b>Gaining market share</b></p>
	<h2>Coating Systems</h2>	<ul style="list-style-type: none"> <li>▪ Coater (Spin, Spray)</li> <li>▪ Inkjet</li> </ul>	<p>→ Growth in line with the market</p> <p>→ <b>New growth opportunities with disrupting solution</b></p>
	<h2>Bonding Systems</h2>	<ul style="list-style-type: none"> <li>▪ Temporary Bonding</li> <li>▪ Permanent Bonding (incl. Hybrid Bonding)</li> </ul>	<p>→ Growth in line with the market</p> <p>→ <b>Gaining market share</b></p> <p>→ <b>New growth opportunities with disrupting solution</b></p>
	<h2>Photomask Equipment</h2>	<ul style="list-style-type: none"> <li>▪ Photomask Equipment</li> <li>▪ Wafer Cleaning</li> </ul>	<p>→ Growth in line with the market</p> <p>→ <b>New growth opportunities with disrupting solution</b></p>

# Based on our business foundation we see further potential beyond



(T = Target, A = Ambition)

1) Preliminary and not-audited number.

2) Analysts' consensus FY 2023 sales as of 21 February 2023 = € 334.4 million